

Abstracts

Time Domain Electromagnetic Analysis of a Via in a Multilayer Computer Chip Package

W.D. Becker, P. Harms and R. Mittra. "Time Domain Electromagnetic Analysis of a Via in a Multilayer Computer Chip Package." 1992 MTT-S International Microwave Symposium Digest 92.3 (1992 Vol. III [MWSYM]): 1229-1232.

The determination of an equivalent circuit to approximate the behavior of an interconnect in a computer package is an important step in the evaluation of the computer's performance. This paper presents a methodology for deriving an equivalent circuit of a via using a time-domain full-wave solution of Maxwell's equations.

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